

#### **APPLICATIONS**

- Rectification
- Freewheel Diode
- DC Motor Control
- Power Supplies
- Welding
- Battery Chargers

#### **FEATURES**

■ High Surge Capability

#### **VOLTAGE RATINGS**

Repetitive Peak Reverse Voltage V <sub>RRM</sub> V	Conditions
2000	$V_{RSM} = V_{RRM} + 100V$
1400	
1000	
600	
	Reverse Voltage V RRM V 2000 1400 1000

Lower voltage grades available.

M for M16 thread. K for 3/4" - 16UNF thread, R for reverse polarity.

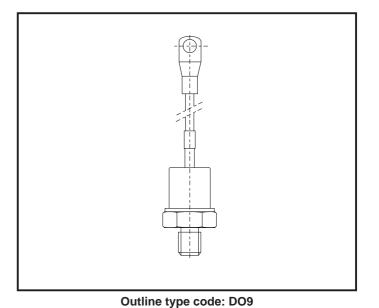
#### **CURRENT RATINGS**

Symbol	Parameter	Conditions	Max.	Units
Single Side Cooled				
I <sub>F(AV)</sub>	Mean forward current	Half wave resistive load, $T_{case} = 100^{\circ}C$	335	А
I <sub>F(RMS)</sub>	RMS value	T <sub>case</sub> = 100°C	525	А
I <sub>F</sub>	Continuous (direct) forward current	T <sub>case</sub> = 100°C	440	А

DS4086-4.0 January 2000

# KEY PARAMETERS

I <sub>F(AV)</sub>	335A
	6000A



See Package Details for further information.

## TV30

#### SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
I <sub>FSM</sub>	Surge (non-repetitive) forward current	10ms half sine; T <sub>case</sub> = 175°C	4.8	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_{R} = 50\% V_{RRM} - 1/4 \text{ sine}$	115 x 10 <sup>6</sup>	A <sup>2</sup> s
I <sub>FSM</sub>	Surge (non-repetitive) forward current	10ms half sine; T <sub>case</sub> =175°C	6.0	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 0$	180 x 10 <sup>3</sup>	A <sup>2</sup> s

#### THERMAL AND MECHANICAL DATA

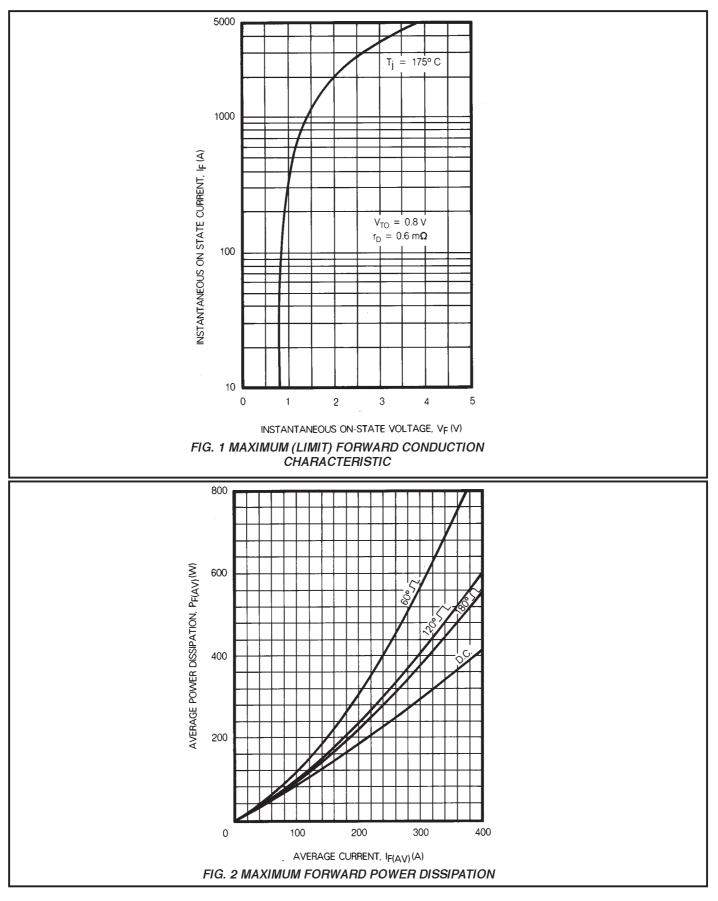
Symbol	Parameter	Conditions	Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance - junction to case	dc	-	0.13	°C/W
R <sub>th(c-h)</sub>	Thermal resistance - case to heatsink	Mounting torque 35.0Nm with mounting compound	-	0.06	°C/W
Ŧ	Virtual junction temperature	Forward (conducting)	-	175	°C
T <sub>vj</sub>		Reverse (blocking)	-	175	°C
T <sub>stg</sub>	Storage temperature range		-55	200	°C
-	Mounting Torque		30.0	35.0	Nm

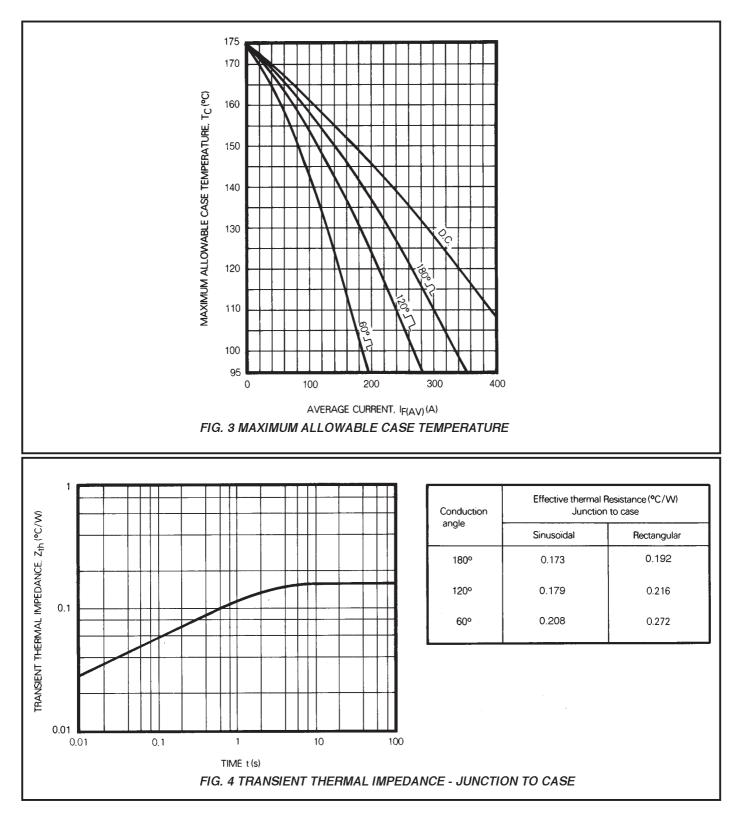
### **CHARACTERISTICS**

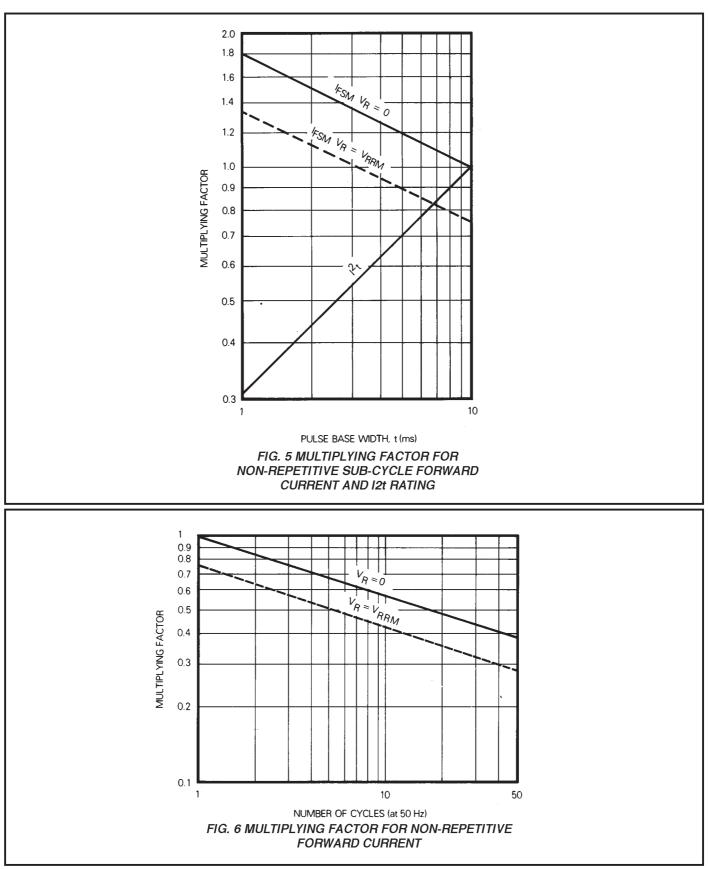
Symbol	Parameter	Conditions	Тур.	Max.	Units
$V_{FM}$	Forward voltage	At 1000A peak, T <sub>case</sub> = 25°C	-	1.4	V
I <sub>RRM</sub>	Peak reverse current	At $V_{RRM}$ , $T_{case} = 175^{\circ}C$	-	20	mA
Q <sub>s</sub>	Total stored charge	I <sub>F</sub> = 200A, dI <sub>RR</sub> /dt = 20A/μs, T <sub>case</sub> = 25°C	300*	-	μC
I <sub>RM</sub>	Peak recovery current		90*	-	А
t <sub>rr</sub>	reverse recovery time			-	μs
V <sub>TO</sub>	Threshold voltage	At $T_{vj} = 175^{\circ}C$	-	0.8	V
r <sub>T</sub>	Slope resistance	At $T_{vj} = 175^{\circ}C$	-	0.6	mΩ

\*Typical values.

#### **CURVES**







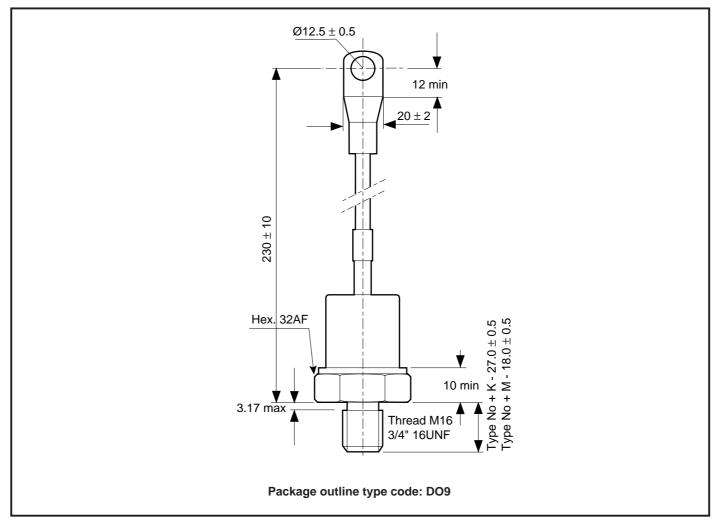
**TV30** 

5/7

# TV30

#### **PACKAGE DETAILS**

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



#### **ASSOCIATED PUBLICATIONS**

Title	Application Note	
	Number	
Calculating the junction temperature or power semiconductors	AN4506	
Thyristor and diode measurement with a multi-meter	AN4853	
Use of $V_{TO}$ , $r_{T}$ on-state characteristic	AN5001	

#### POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group continues to offer high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the up to date CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete solution (PACs).

#### HEATSINKS

Power Assembly has it's own proprietary range of extruded aluminium heatsinks. They have been designed to optimise the performance or our semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest Sales Representative or the factory.



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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

No Annotation: The product parameters are fixed and the product is available to datasheet specification.

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